

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the applications:

Listing of Claims:

What is claimed is:

1. (Previously Presented) An integrated circuit, comprising:
a substrate;
at least one area of dielectric material disposed on said substrate;
at least one area of metal material disposed on said substrate;
a bondpad associated with said at least one area of dielectric material and said at least one area of metal material; and
a circuitry for generating a negative capacitance, said circuitry comprising:
at least two transistors;
at least two resistors; each resistor of said at least two resistors being coupled to each of said at least two transistors; and
a capacitor coupled to a first transistor of said at least two transistors and a first resistor of said at least two resistors; wherein said circuitry generates said negative capacitance of a value to compensate for a capacitance associated with said bondpad, said circuitry being coupled to said bondpad.
2. (Original) The integrated circuit as claimed in claim 1, wherein a value of said negative capacitance is approximately equal in magnitude to said capacitance associated with said bondpad.
3. (Canceled)

4. (Canceled)

5. (Previously Presented) The integrated circuit as claimed in claim 1, wherein said negative capacitance generated by said circuitry is dependent upon component values of said at least two resistors and said capacitor.

6. (Original) The integrated circuit as claimed in claim 1, wherein said circuitry is fabricated within the substrate.

7. (Previously Presented) An apparatus, comprising:
a housing;
a substrate disposed within said housing;
at least one area of dielectric material disposed on said substrate;
at least one area of metal material disposed on said substrate;
a bondpad associated with said at least one area of dielectric material and said at least one area of metal material, said bondpad being coupled to said housing; and
a circuitry for generating a negative capacitance, said circuitry comprising:
at least two transistors;
at least two resistors; each resistor of said at least two resistors being coupled to each of said at least two transistors; and
a capacitor coupled to a first transistor of said at least two transistors and a first resistor of said at least two resistors; wherein said circuitry generates said negative capacitance of a value to compensate for a capacitance associated with said bondpad, said circuitry being coupled to said bondpad.

8. (Original) The apparatus as claimed in claim 7, wherein said value of said negative capacitance is approximately equal in magnitude to said capacitance associated with said bondpad.

9. (Canceled)

10. (Canceled)

11. (Previously Presented) The apparatus as claimed in claim 7, wherein said negative capacitance generated by said circuitry is dependent upon a component values of said at least two resistors and said capacitor.

12. (Original) The apparatus as claimed in claim 11, wherein said negative capacitance generated by said circuitry is dependent upon a ratio of a first resistor to a second resistor multiplied by a value of said capacitor.

13. (Original) The apparatus as claimed in claim 7, wherein said circuitry is fabricated within the substrate.

14. (Previously Presented) An apparatus, comprising:
a substrate;
at least one area of dielectric material disposed on said substrate;
at least one area of metal material disposed on said substrate;
a bondpad associated with said at least one area of dielectric material and said at least one area of metal material; and
a circuitry for generating a negative capacitance, said circuitry comprising:
at least two transistors;
at least two resistors; each resistor of said at least two resistors being coupled to each of said at least two transistors; and
a capacitor coupled to a first transistor of said at least two transistors and a first resistor of said at least two resistors; wherein said circuitry generates said negative capacitance of a value to compensate for a capacitance associated with said bondpad, said circuitry being coupled to said bondpad.

15. (Canceled)

16. (Canceled)

17. (Previously Presented) The apparatus as claimed in claim 14, wherein said negative capacitance generated by said circuitry is dependent upon component values of said at least two resistors and said capacitor.

18. (Original) The apparatus as claimed in claim 17, wherein said negative capacitance generated by said circuitry is dependent upon a ratio of a first resistor to a second resistor multiplied by a value of said capacitor.

19. (Canceled)

20. (Canceled)